

**IN THE SPECIFICATION:**

**Please amend Page 3, Paragraph 2 as follows:**

In spite of these advantages, however, the hybrid structure is expected to have a problem that, since [[not]] all the excitation light emitted from the LED chips will not be converted into visible light by the phosphor film, a part of the excitation light will be reflected on the resin covering the insulating substrate, to deteriorate the resin. Use of a ceramic substrate works to counter this problem. However, because of being expensive, the ceramic substrate is not suitable for [[the]] this use if it requires numerous chips and so requires a large area. Other means can be also considered, such as reducing the amount of excitation light that is reflected from the phosphor film, or processing the substrate to be light resistant, in particular to be ultraviolet resistant. However, there is a limitation in preventing the excitation light from reflection. In addition, new problems are considered to arise. One example is that a heat emitted from the LED chip will be accumulated thereby deteriorating thermal-dissipation characteristic, in a case where, in an attempt to delay deterioration, a substrate is used that has a thick resin layer as a means to process the substrate to be light resistant. These problems similarly happen for the display in which numerous LED chips are disposed (in this specification, a combination of an illumination apparatus and a display is defined as “light emission apparatus”).

**Please amend Page 8, Paragraph 11 as follows:**

FIG. 11A – FIG. 11C ~~describe~~ describes side-surface views of the illumination apparatus, for the purpose of showing the mounting condition of the illumination apparatus relating to the present invention;

**Please amend Page 9, Paragraphs 1 and 2 as follows:**

FIG. 13 is slanting view and exploded view of the illumination apparatus of the second embodiment of the present invention; ~~and~~

FIG. 14 is a sectional view of the illumination apparatus relating to the second embodiment of the present invention; and

FIG. 15 is a partly enlarged view of an LED chip with a phosphor layer between the cover and substrate.

**Please amend Page 10, Paragraph 2 as follows:**

As shown in this drawing, the substrate section 2 is formed by accumulating the following: a metal substrate 20 whose center part corresponding, in position and form, to the concave 2a has a concave 20a; a resin layer 21 that covers the entire surface of the metal substrate 20; a first metal layer 22a that is placed at an area, on the resin layer 21, that corresponds to the concave 2a; and a second metal layer 22b that is placed at an area, on the resin layer 21 except where there is the concave 2a. Moreover, a resin layer 23, a metal layer 24, and a resin layer 25 are accumulated over the second metal layer ~~[[22a]]~~ 22b (i.e. at an area except where there is the concave 2a), in the stated order.